



THE DATASHEET OF EVP-AWBD2A



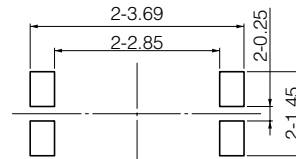
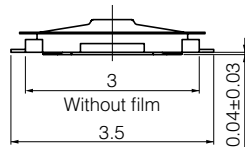
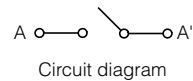
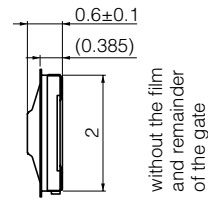
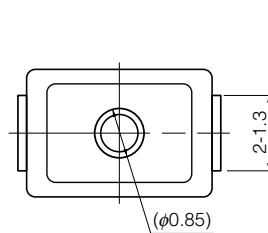
■ Dimensions in mm (not to scale)

EVPAW

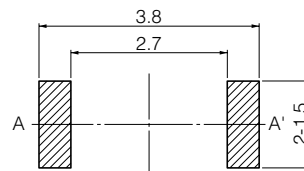
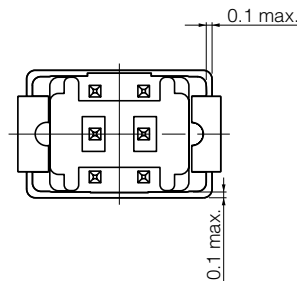
(Embossed Taping)
Terminal without cutout type

General dimension tolerance : ± 0.05
() dimensions are reference dimensions.

This reference specifications are subject to change.



Stencil mask plan



PWB land pattern for reference

Soldering thickness $t=0.08 \pm 0.01$

*Soldering failure may occur depending on applied solder amount, so, please consider to use our recommended stencil and land pattern desing.

Part Numbers	Operating Force	Height	Operating Life
EVPAWBA2A	1.6 N	0.6 mm	500000 cycles
EVPAWCA2A	2.4 N	0.6 mm	500000 cycles
EVPAWEA2A	3.3 N	0.6 mm	300000 cycles

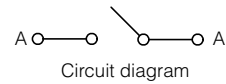
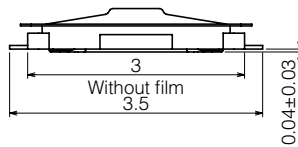
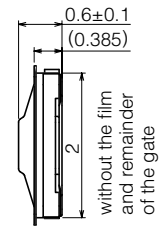
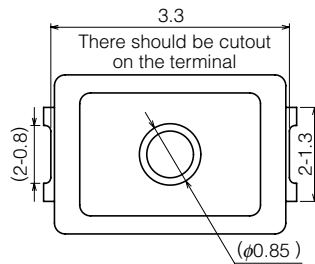
■ Dimensions in mm (not to scale)

EVPAW

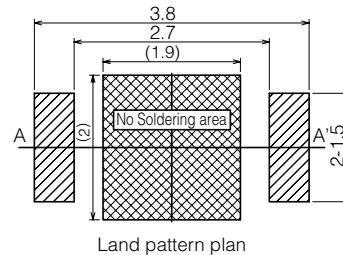
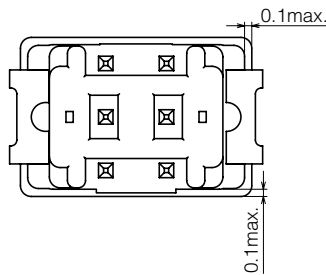
(Embossed Taping)
Terminal with cutout type

General dimension tolerance : ± 0.05
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The thickness of the solder stencil shall be 0.1 mm, and the opening ratio of the solder stencil to a land pattern shall be 60 to 100 % (recommend 80 %.)



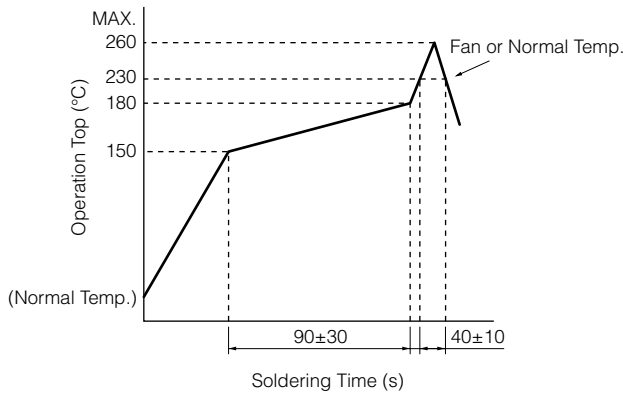
* Soldering failure may occur depending on applied solder amount, so, please consider to use our recommended stencil and land pattern desing.

▨ : Recommended land pattern area
▩ : No soldering area

- Any land pattern or via holes shall not be provided at ▩ area.
- If it's necessary to design land pattern or via holes at ▩ area, please apply resist to them to protect their metal part completely.
- If their metal parts are not protected completely, short circuit failure may occur.
- Besides, there should be convexoconcave by designing additional pattern, it may cause swith tilt, influence on solder-ability or flux intrusion after reflow soldering.
- Therefore, please study any influence of addition land pattern or via holes at ▩ area in advance.

Part Numbers	Operating Force	Height	Operating Life
EVPAWBD4A	1.6 N	0.6 mm	500000 cycles
EVPAWCD4A	2.4 N	0.6 mm	500000 cycles
EVPAWED4A	3.3 N	0.6 mm	300000 cycles

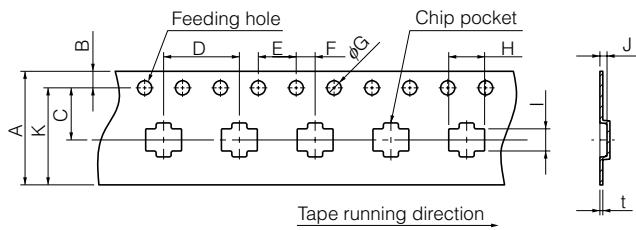
Recommended Reflow Soldering Conditions



*Reflow temperature may vary by location even in the same reflow condition. Please check the reflow temperature at terminals and at the top of a switch to make sure the both temperatures are within the specification. If even one of them is out of the specifications, please adjust.

Embossed Carrier Taping

Tape width=12.0 mm

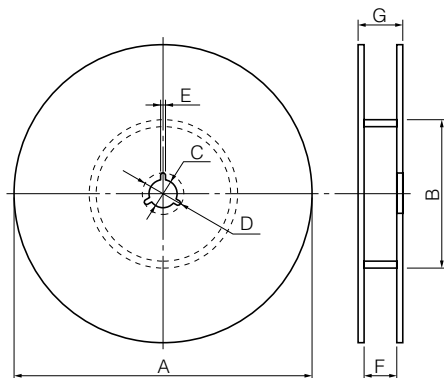


Taping condition : Lack of products in the middle of taping should be one MAX, but total quantity specified in the specifications should be secured.
Peeling off strength of top tape : It should be within 0.2N to 1.0N at 165 degree in peeling off angle.
Joint of carrier tape : One joint per one reel may exist.

Unit: mm

Part No.	Height	A	B	C	D	E	F	G	H	I	J	K	t
EVPAW	0.6	12.0±0.3	1.75±0.10	5.5±0.1	8.0±0.1	4.0±0.1	2.0±0.1	1.5±0.3	3.8±0.2	2.3±0.2	0.75±0.20	(10.25)	0.3 ^{+0.15} _{-0.10}

Standard Reel Dimensions in mm (not to scale)





Item	A	B	C	D	E
Rate (mm)	φ380.0±2.0	φ80.0±1.0	φ13.0±0.5	φ21.0±1.0	2.0±0.5

Item	F	G
Rate (mm)	13.5±1.0	17.5±1.0

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